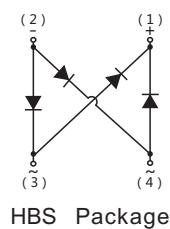


### Features

- Surface mount bridge, small package;
- Ideal for printed circuit boards;
- Glass passivated chip junction;
- High forward current capability up to 8.0A;
- High surge current capability;
- High heat dissipation capability;
- Low profile package;
- Low forward voltage drop;
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0;

### Mechanical Data

- Case: HBS;  
Epoxy meets UL-94V-0 Flammability rating;
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102;
- High temperature soldering guaranteed:  
Solder Reflow 260°C, 10seconds;
- Polarity: As marked on body;
- Marking: Type number;



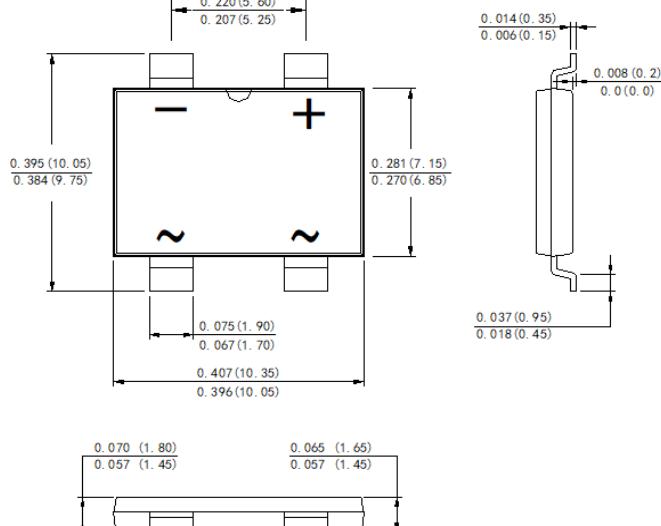
### VOLTAGE RANGE

200 to 1000 Volts

### CURRENT

8.0 Amperes

HBS



Dimensions in inches and (millimeters)

### Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

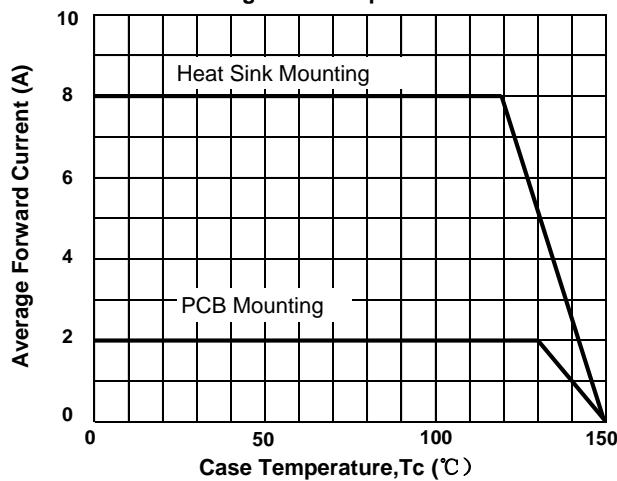
Parameter	Symbols	RHBS802	RHBS804	RHBS806	RHBS808	RHBS810	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	200	400	600	800	1000	V
Average Rectified Output Current	$I_o$			8.0			A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$			200			A
$I^2t$ Rating for Fusing	$I^2t$			166			$A^2S$
Maximum Forward Voltage at 1.0 A	$V_F$			0.83 (max.)			V
Maximum Forward Voltage at 8.0 A	$V_F$			1.3			V
Maximum DC Reverse Current @ $T_A=25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125\text{ }^\circ\text{C}$	$I_R$			0.20 100			$\mu\text{A}$
Maximum reverse recovery time ( $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$ )	$Tr$		150	250	500		nS
Typical Junction Capacitance ( Note1 )	$C_J$			48			pF
Typical Thermal Resistance ( Note2 )	$R_{BJA}$ $R_{BJC}$ $R_{BLJ}$			70.0 15.0 22.0			$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$			-55 ~ +150			$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

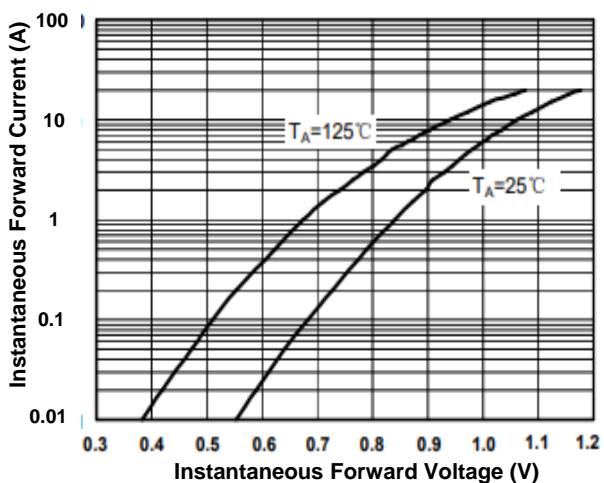
2. Mounted on glass epoxy PC board with  $4 \times 1.5'' \times 1.5''$  (3.81x3.81 cm) copper pad.

## RATING AND CHARACTERISTIC CURVES (RHBS802 THRU RHBS810)

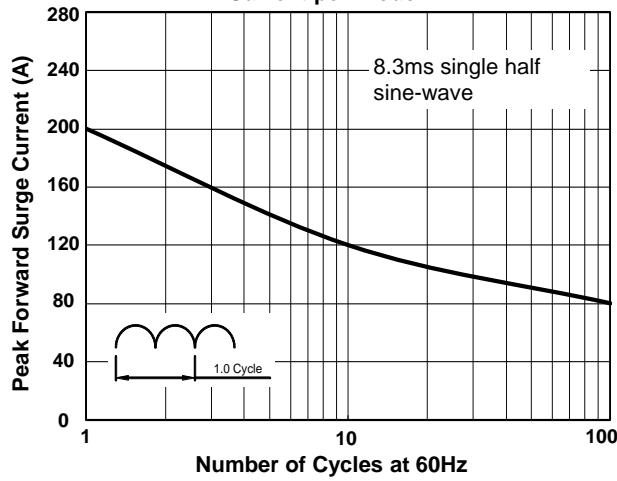
**FIG.1 Derating Curve Output Rectified Current**



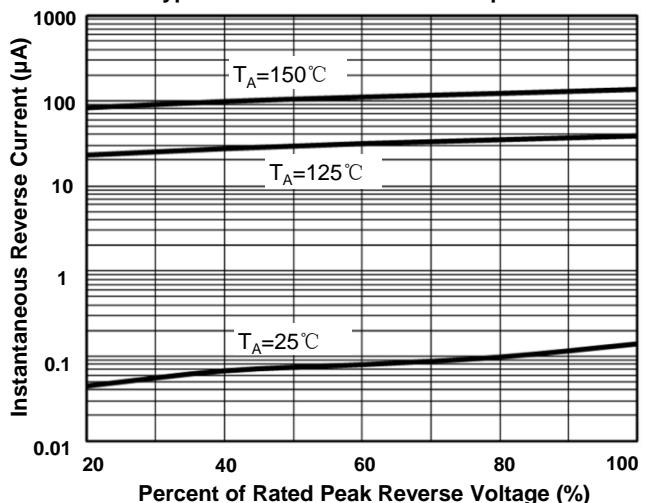
**FIG.2 Typical Forward Characteristics per Diode**



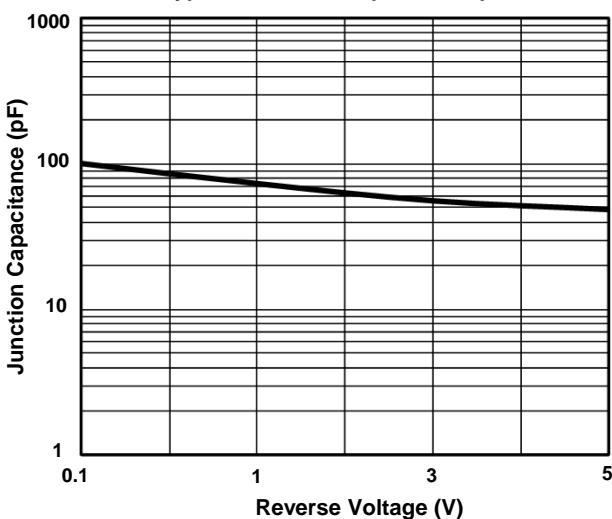
**FIG.3 Maximum Non-Repetitive Peak Forward Surge Current per Diode**



**FIG.4 Typical Reverse Characteristics per Diode**



**FIG.5 Typical Junction Capacitance per Diode**



**Suggested PCB printfoot layout**

Unit: inches (mm)

